

Title (en)
TIN ALLOY SOLDER COMPOSITIONS

Title (de)
LÖTZUSAMMENSETZUNGEN AUS ZINNLEGIERUNG

Title (fr)
COMPOSITIONS DE BRASURE A BASE D'ALLIAGE D'ETAIN

Publication
EP 1880032 A2 20080123 (EN)

Application
EP 06759560 A 20060511

Priority
• US 2006018235 W 20060511
• US 67986905 P 20050511

Abstract (en)
[origin: WO2006122240A2] A lead-free and bismuth-free solder alloy composition for electronic assembly applications having reduced toxicity. The alloy composition comprises about 0.01% to about 4.5% silver; about 0.01% to about 3% copper; about 0.002% to about 5.0% antimony; about 85% to about 99% tin and about 0.002% to about 1% of either nickel or cobalt. The alloy composition has a melting temperature of about 217° C, with superior wetting and mechanical strength making the alloy composition well suited for electronic circuit board manufacture and lead less component bumping or column arrays, and replacement of conventional tin-lead solders.

IPC 8 full level
C22C 13/02 (2006.01); **B23K 35/26** (2006.01); **C22C 13/00** (2006.01)

CPC (source: EP US)
B23K 35/0244 (2013.01 - EP US); **B23K 35/262** (2013.01 - EP US); **C22C 13/00** (2013.01 - EP US); **C22C 13/02** (2013.01 - EP US); **B23K 2101/36** (2018.07 - EP US)

Cited by
CN111230355A

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2006122240 A2 20061116; **WO 2006122240 A3 20070201**; CA 2607286 A1 20061116; EP 1880032 A2 20080123; EP 1880032 A4 20090304; MX 2007013971 A 20080222; US 2006263234 A1 20061123

DOCDB simple family (application)
US 2006018235 W 20060511; CA 2607286 A 20060511; EP 06759560 A 20060511; MX 2007013971 A 20060511; US 43229906 A 20060511